External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Impurity	Non hazardous		0.00001	0.01	0.00001
	Pure metal	Copper (Cu)	7440-50-8	0.12998	99.99	0.11654
			Subtotal	0.12999	100	0.11655
Die Attach		Aromatic Polyester Resin	60088-52-0	0.01506	2.5	0.0135
		Paraffin wax	8002-74-2	0.04216	7.0	0.0378
		Epoxy resin system		0.12046	20.0	0.108
		Silver (Ag)	7440-22-4	0.42462	70.5	0.3807
			Subtotal	0.6023	100	0.54
Lead Frame		Phosphorous (P)	7723-14-0	0.00465	0.03	0.00417
		Zinc (Zn)	7440-66-6	0.0155	0.1	0.0139
		Iron (Fe)	7439-89-6	0.37209	2.4	0.3336
		Copper (Cu)	7440-50-8	15.11137	97.47	13.54833
			Subtotal	15.50361	100	13.9
Mould Compound		Phenol Formaldehyde resin (generic)	9003-35-4	1.95189	2.5	1.75
		Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	7.80757	10.0	7
		Silica fused	60676-86-0	66.36436	85.0	59.5
		Metal hydroxide		1.56151	2.0	1.4
		Carbon black	1333-86-4	0.39038	0.5	0.35
			Subtotal	78.07571	100	70
Post-plating	Pure metal	Tin (Sn)	7440-31-5	3.79225	100.0	3.4
			Subtotal	3.79225	100	3.4
Die	Doped silicon	Silicon (Si)	7440-21-3	1.89612	100.0	1.7
			Subtotal	1.89612	100	1.7
			Total	99.99998	100	89.65655

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